


	#	Layer	Thickness	Description	Dk	Df	Note
		Top Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts
	1	Top Side	0.030mm	Starting foil 1/4oz. after plating and processing			
			0.065mm	Prepreg IPC-4101/127/128	3,5	0,011	FR-4.1 filled, halogen free
	2	Inner Layer 1	0.030mm	Starting foil 1/4oz. after plating and processing			
			0.125mm	Prepreg IPC-4101/127/128	3,7	0,011	FR-4.1 filled, halogen free
	3	Inner Layer 2	0.035mm	ED Base Copper			
			0.100mm	Core IPC-4101/127/128	3,8	0,011	FR-4.1 filled, halogen free
	4	Inner Layer 3	0.035mm	ED Base Copper			
			0.125mm	Prepreg IPC-4101/127/128	3,7	0,011	FR-4.1 filled, halogen free
	5	Inner Layer 4	0.035mm	ED Base Copper			
			0.100mm	Core IPC-4101/127/128	3,8	0,011	FR-4.1 filled, halogen free
	6	Inner Layer 5	0.035mm	ED Base Copper			
			0.125mm	Prepreg IPC-4101/127/128	3,7	0,011	FR-4.1 filled, halogen free
	7	Inner Layer 6	0.030mm	Starting foil 1/4oz. after plating and processing			
			0.065mm	Prepreg IPC-4101/127/128	3,5	0,011	FR-4.1 filled, halogen free
	8	Bottom Side	0.030mm	Starting foil 1/4oz. after plating and processing			
		Bottom Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts
Total thickness: 0.995mm							

		HDI8_1-(6b)-1_1,00_35_V2.12				
notes:		PCB Thickness Tolerance: ± 10%				
Final copper thickness according to IPC-6012	customer		created			
	pcb name		approved			
	engineer		format	A4, landscape		
Please regard to our sectional design rules: ► www.we-online.com	date					
	Template Revision: 02/2021 by Andreas Schilpp / Michael Kress / Werner Öchslen					